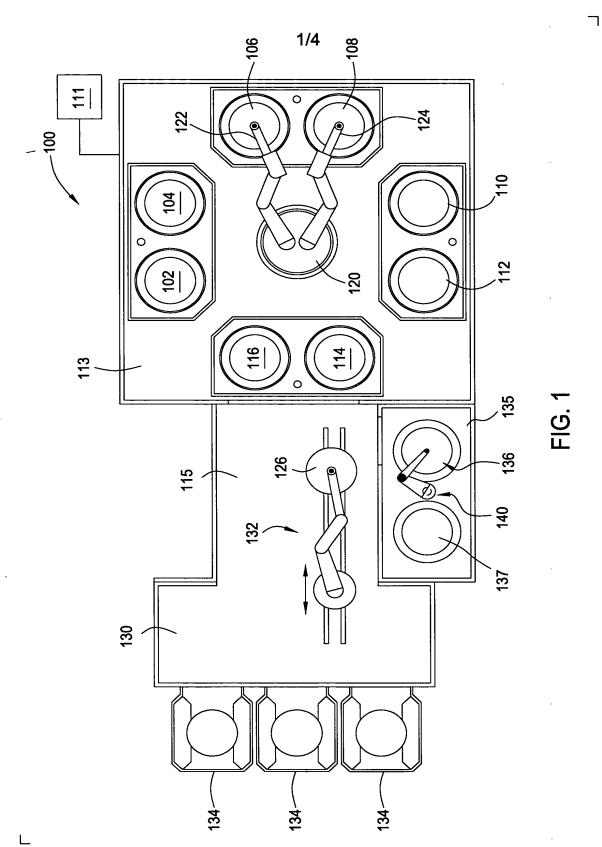
CONF. NO.: UNKNOWN

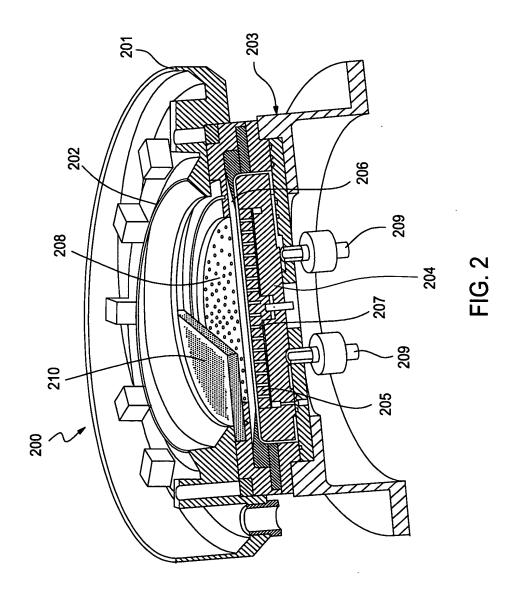
ATTY DKT. NO.: AMAT/8461/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: METHOD AND APPARATUS FOR INFILM DEFECT
REDUCTION FOR ELECTOCHEMICAL COPPER DEPOSITION
INVENTOR: YI-CHIAU HUANG, ET AL.
EXPRESS MAIL NO.: EV351032005US PAGE 1 OF 4



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U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOW
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EXPRESS MAIL NO.: EV351032005US PAGE 2 OF 4

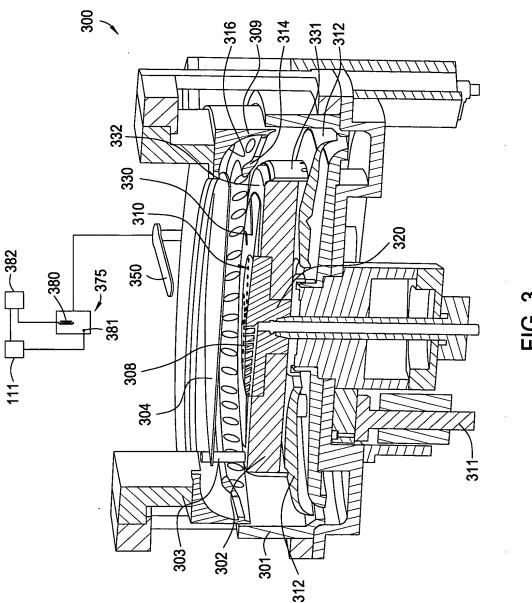
2/4



CONF. NO.: UNKNOWN

ATTY DKT. NO.: AMAT/8461/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOW
FILED: HEREWITH
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CONF. No.: UNKNOWN

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